

S1000-2

PROPERTY	Typical Value	UNIT	Condition	Test Method
Glass Transition Temperature, Tg	185	°C	A	DMA IPC-TM-650 2.4.24.2
Glass Transition Temperature, Tg	180	°C	A	DSC IPC-TM650 2.4.25
Thermal Expansion, Z CTE	45	ppm/°C	A	Before Tg, IPC-TM-650 2.4.41
Thermal Expansion, Z CTE	220	ppm/°C	A	After Tg, IPC-TM-650 2.4.41
Decomposition Temperature, Td	345	°C	A	TMA IPC-TM650 2.4.24.6
Delamination Time, T260	60	minutes	A	TMA IPC-TM650 2.4.24
Delamination Time, T288	20	minutes	A	TMA IPC-TM650 2.4.24
Delamination Time, T300	5	minutes	A	TMA IPC-TM650 2.4.24
Dielectric Constant (Dk)	4.8	-	1 MHz	IPC-TM-650 2.5.5.9
Dissipation Factor (Df)	0.013	-	1 MHz	IPC-TM-650 2.5.5.9
Volume Resistivity	2.20E+08	MΩ·cm	After moisture resistance	IPC-TM-650 2.5.17.1
Surface Resistivity	7.90E+07	MΩ	After moisture resistance	IPC-TM-650 2.5.17.1
Dielectric Breakdown	45+NB	kV	D-48/50+D-0.5/23	IPC-TM-650 2.5.6
Thermal Conductivity	0.62	W/m·K	100	ASTM D5470
Water Absorption	0.1	%	D-24/23	IPC-TM-650 2.6.2.1
Copper Peel Strength	1.38 (7.9)	N/mm (lb/in.)	after solder float 1 oz. EDC Foil	IPC-TM-650 2.4.8
Flammability	94V-0	-	A	UL